

## AMENDMENTS TO THE CLAIMS

Claims 1-10 (Cancelled).

Claim 11. (Original) A method of forming a package for integrated circuits comprising the steps of:

forming an upper board having a set of upper contact members adapted for bonding an upper integrated circuit through signal-carrying contacts formed on an upper surface of said upper board in an upper integrated circuit location and a set of electrically conductive bonding members on a lower surface of said upper board, said upper board having a bonding surface on said lower surface thereof below said upper integrated circuit location;

forming a lower board having a counterpart set of electrically conductive bonding members on an upper surface of said upper board matching said set of electrically conductive bonding members on said lower surface of said upper board and having an aperture passing therethrough below said bonding surface, thereby forming a cavity adapted for holding a lower integrated circuit and a set of wirebond pads disposed about said aperture on a lower surface of said lower board for contacting said second integrated circuit; and

bonding said upper board to said lower board with said set of electrically conductive bonding members.

Claim 12. (Original) A method of forming a package for integrated circuits according to claim 11, further comprising the steps of:

bonding an upper integrated circuit to said upper board and testing the combination of said upper integrated circuit and said upper board;

bonding a lower integrated circuit to said lower board and testing the combination of said lower integrated circuit and said lower board; and

thereafter bonding said upper board to said lower board.